



US00D394080S

United States Patent [19]
Chan

[11] **Patent Number:** **Des. 394,080**
[45] **Date of Patent:** ****May 5, 1998**

[54] **EMBOSSING DEVICE**
[75] **Inventor:** **Yip Kwong Chan, Hong Kong, Hong Kong**
[73] **Assignee:** **Y & H Industrial Limited, New Territories, Hong Kong**
[**] **Term:** **14 Years**

[21] **Appl. No.:** **72,132**
[22] **Filed:** **Jun. 9, 1997**
[51] **LOC (6) Cl.** **08-05**
[52] **U.S. Cl.** **D18/19; D18/14**
[58] **Field of Search** **D18/14, 15, 19; D19/65; D8/49-51; 156/220, 219; 400/134.6, 134.4; 101/31.1, 28, 327**

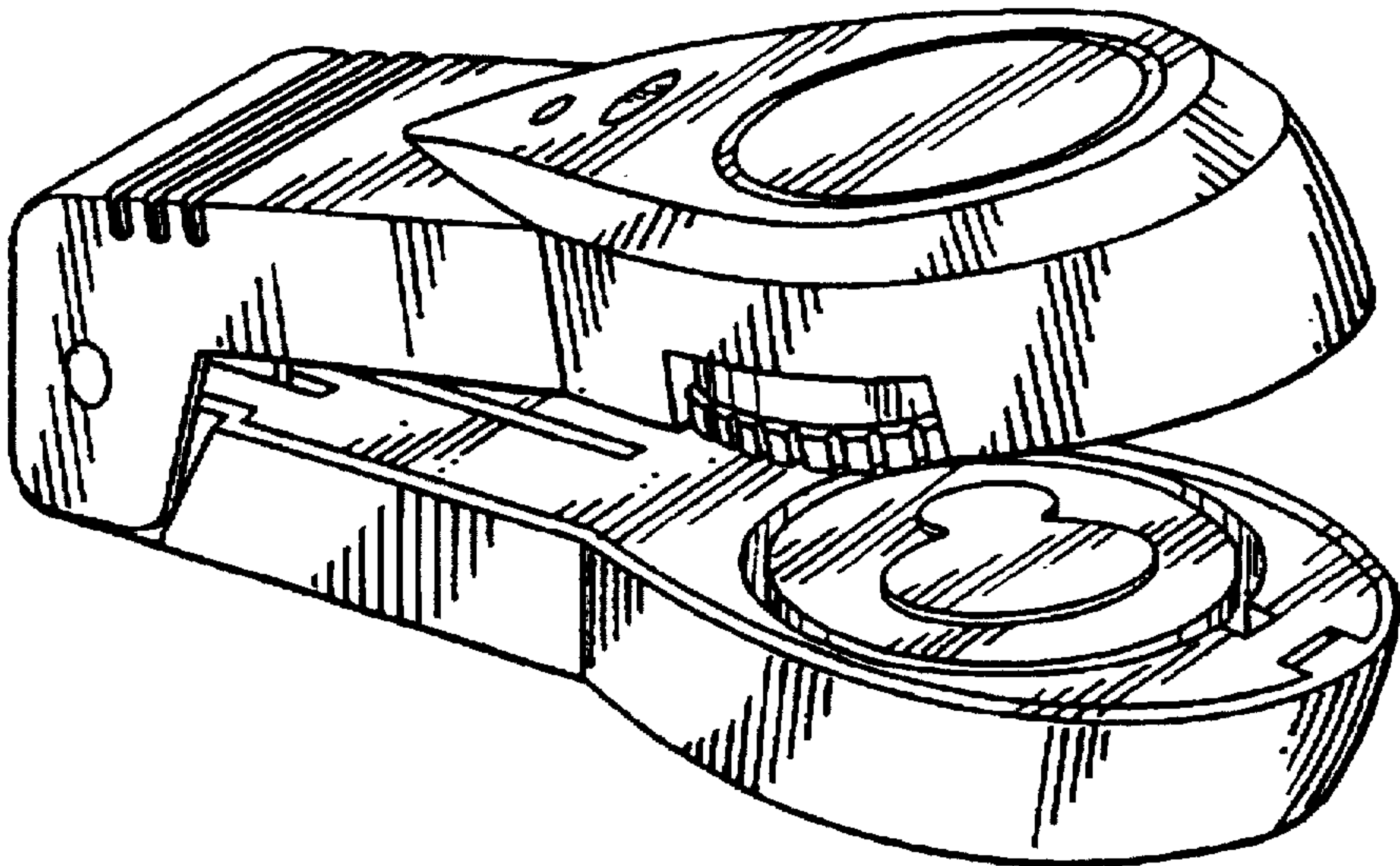
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Primary Examiner—Louis S. Zarfes
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Attorney, Agent, or Firm—Leydig, Voit & Mayer, Ltd.

[57] **CLAIM**
The ornamental design for an embossing device, as shown and described.

DESCRIPTION
FIG. 1 is a top, front end and right side perspective view of an embossing device showing my new design;
FIG. 2 is a top plan view thereof;
FIG. 3 is a left side elevational view thereof;
FIG. 4 is a right side elevational view thereof;
FIG. 5 is bottom plan view thereof;
FIG. 6 is a front end elevational view thereof; and,
FIG. 7 is a rear end elevational view thereof.

1 Claim, 4 Drawing Sheets



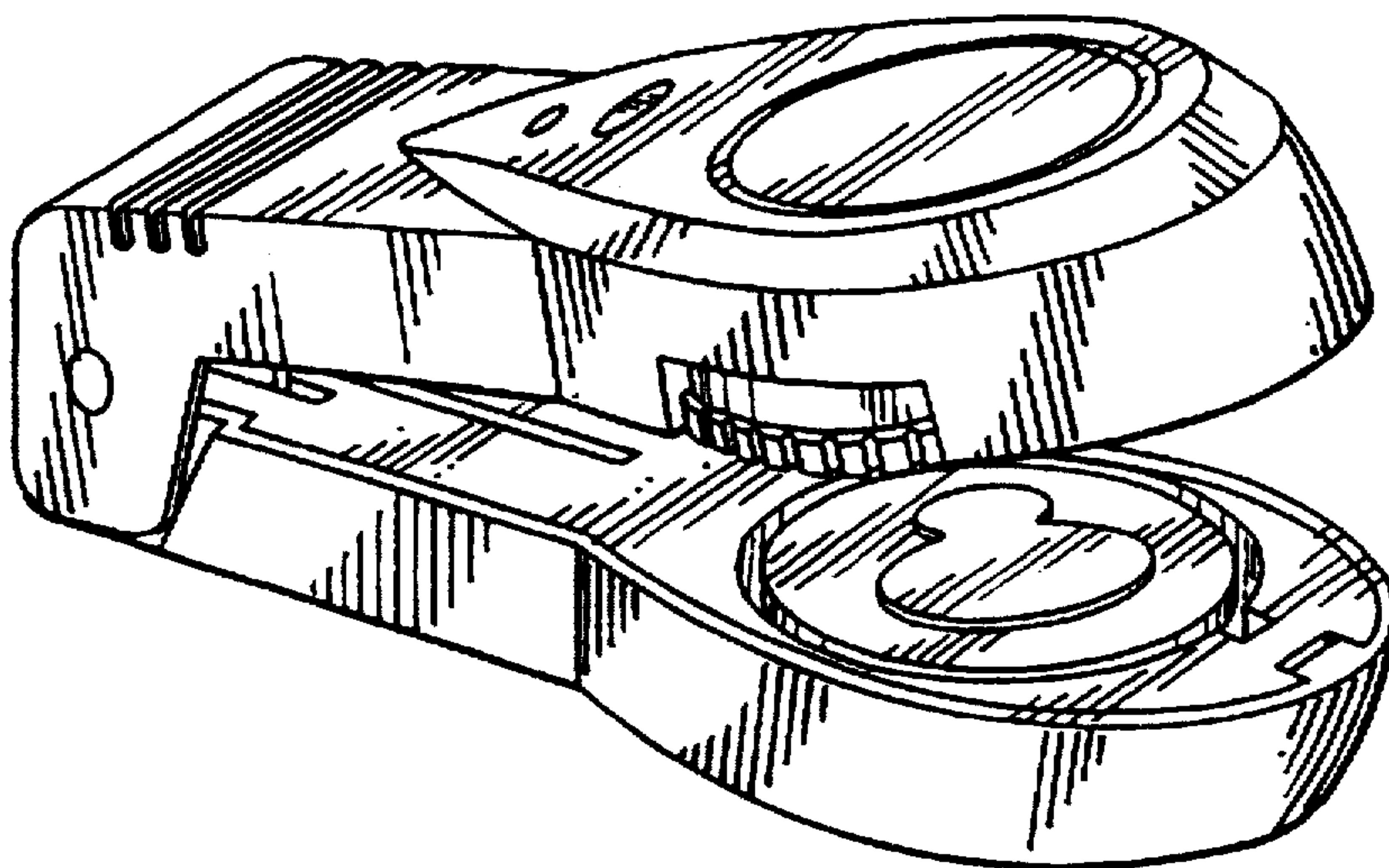


FIG. 1

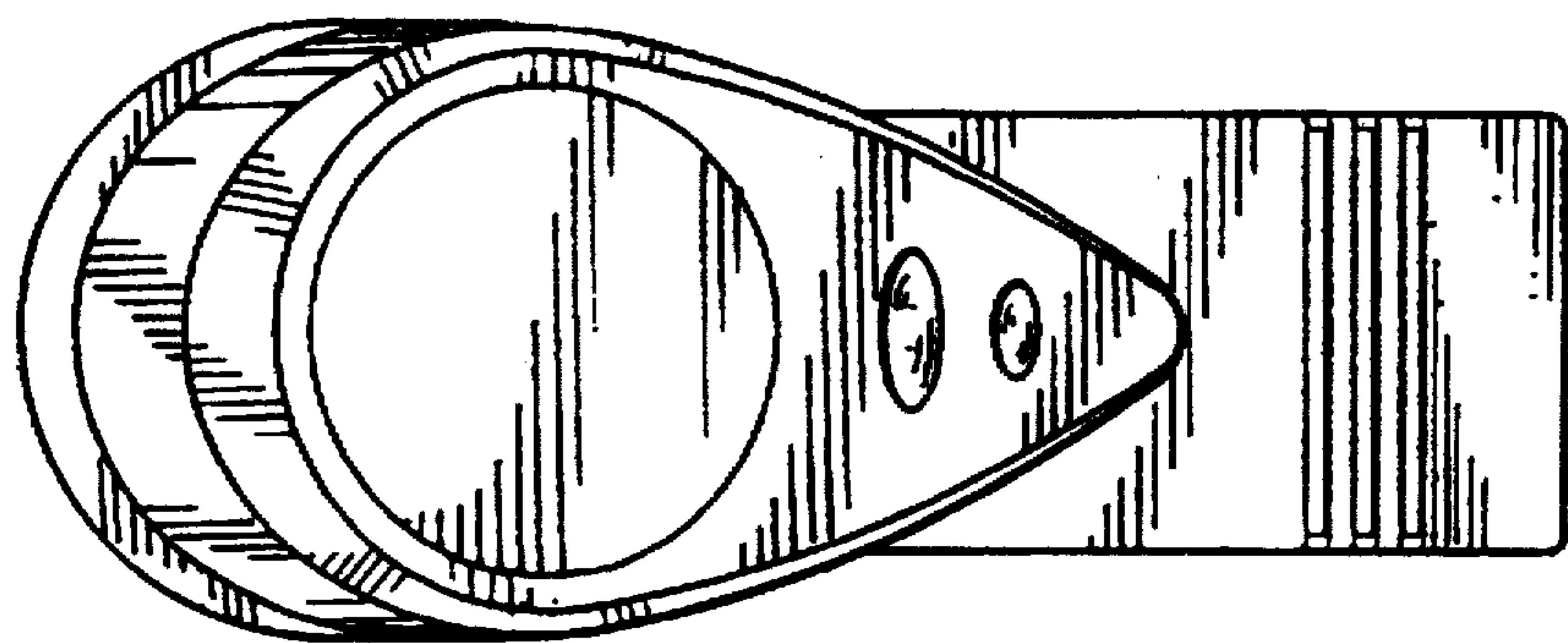


FIG. 2

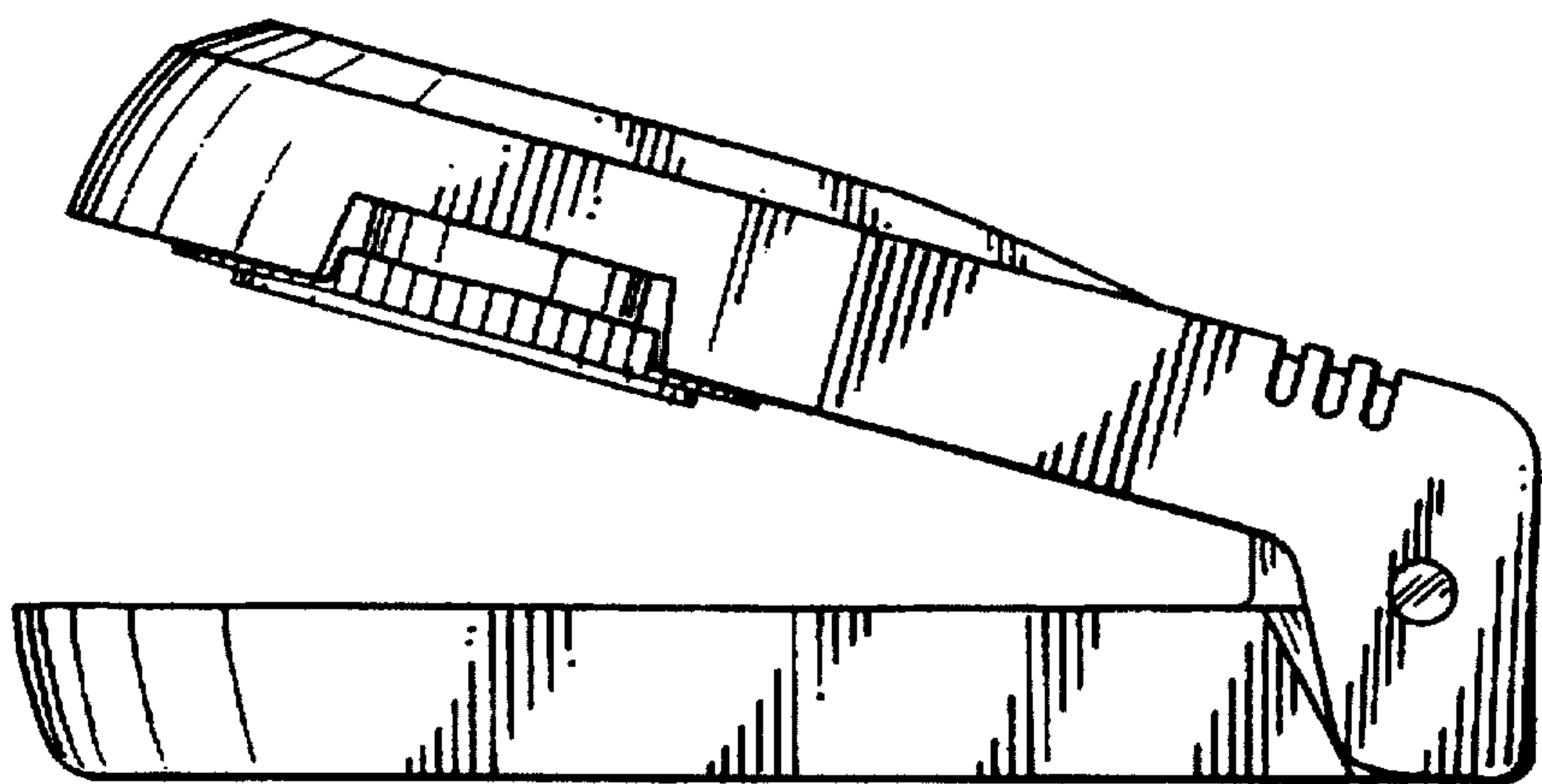


FIG. 3

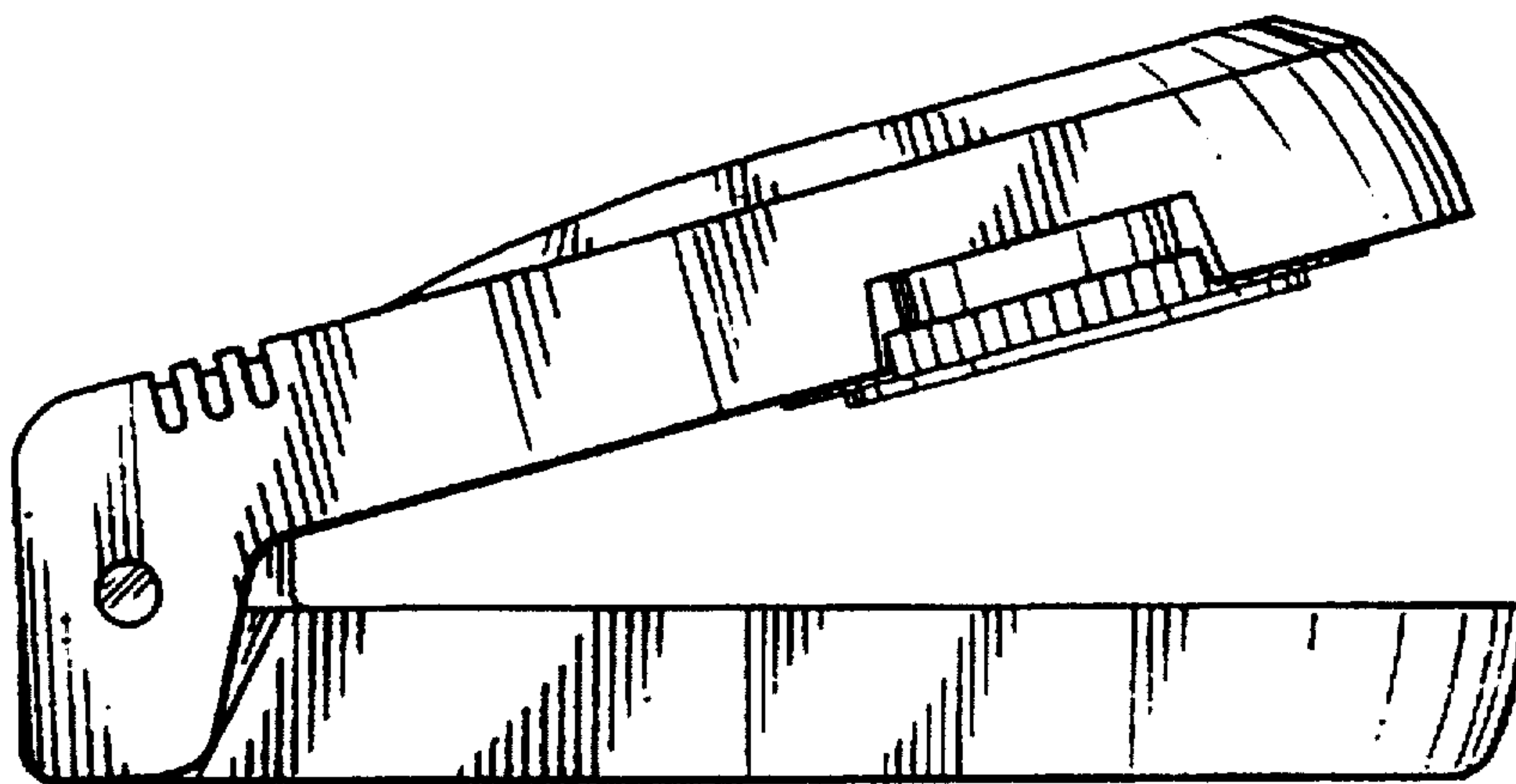


FIG. 4

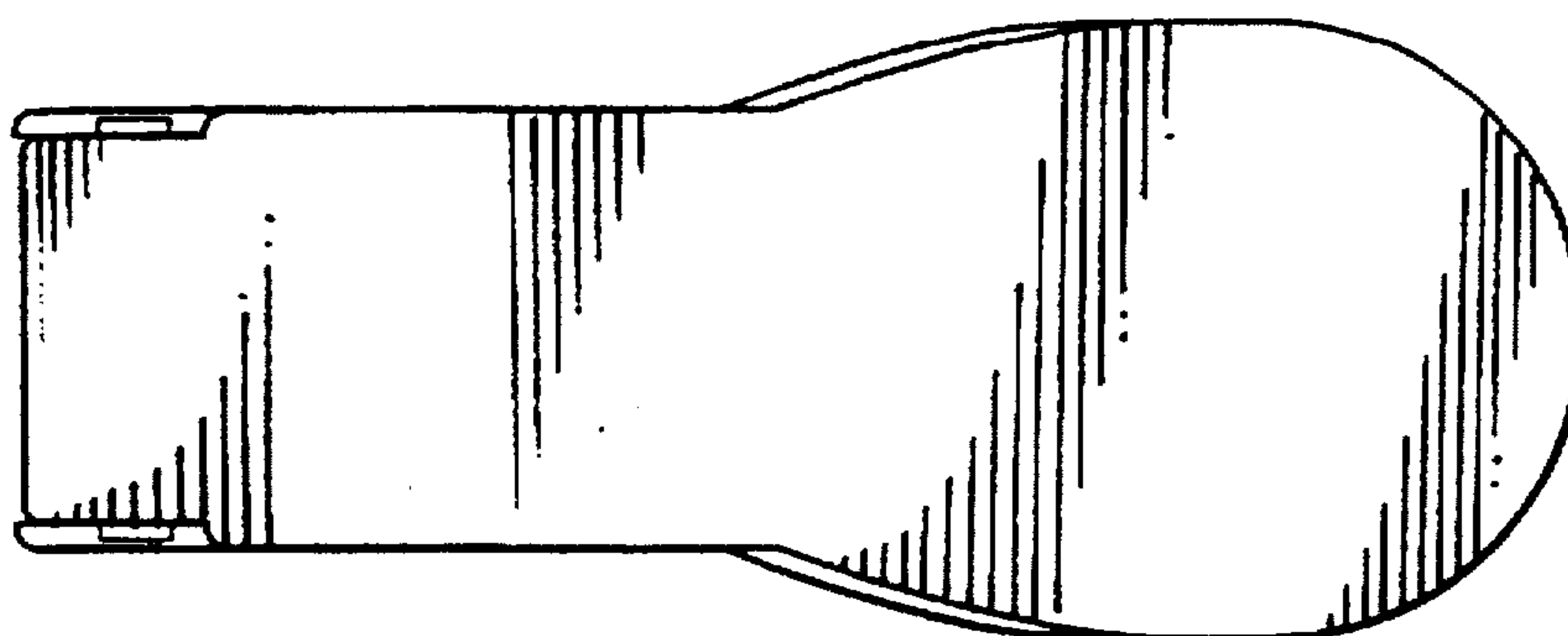


FIG. 5

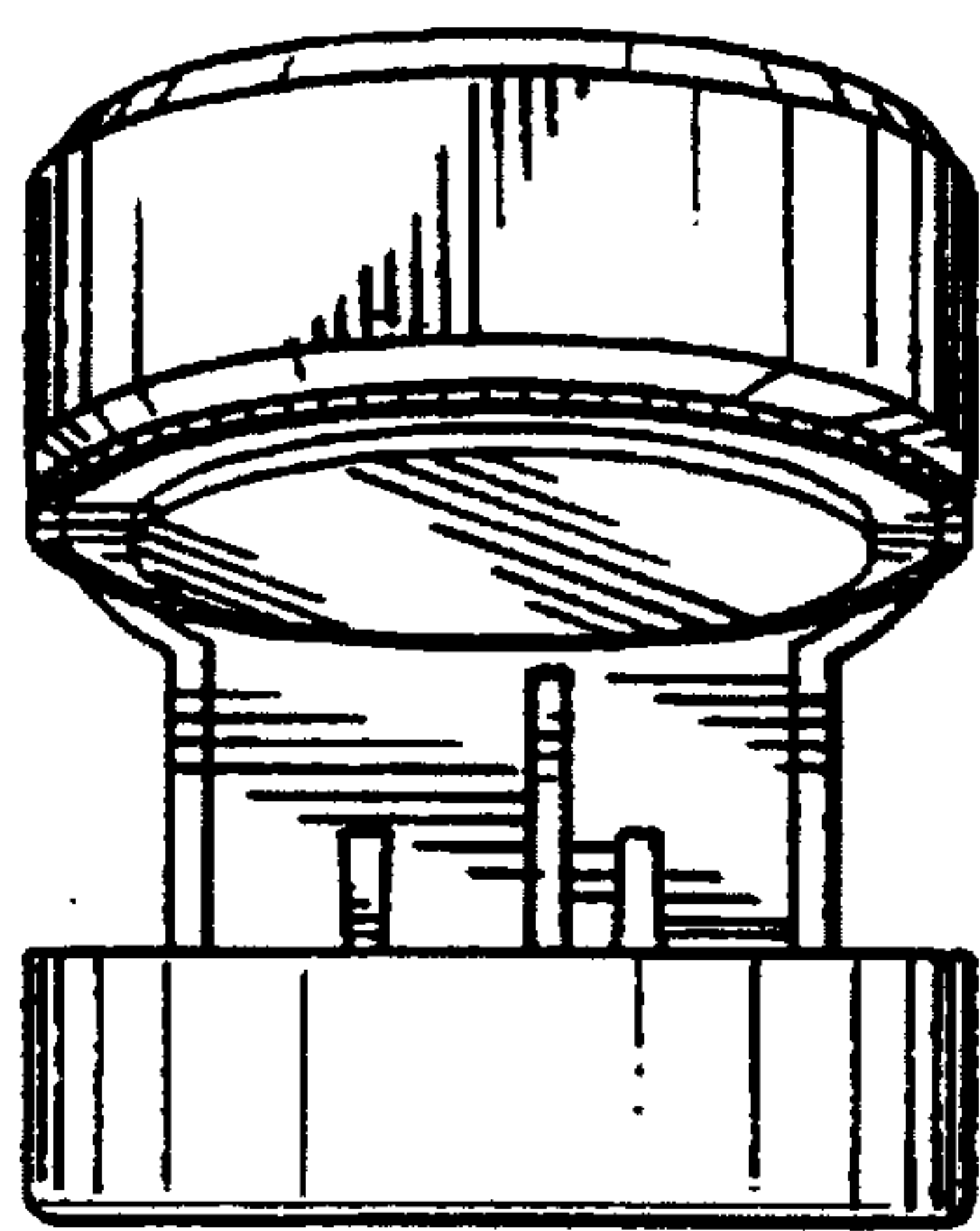


FIG. 6

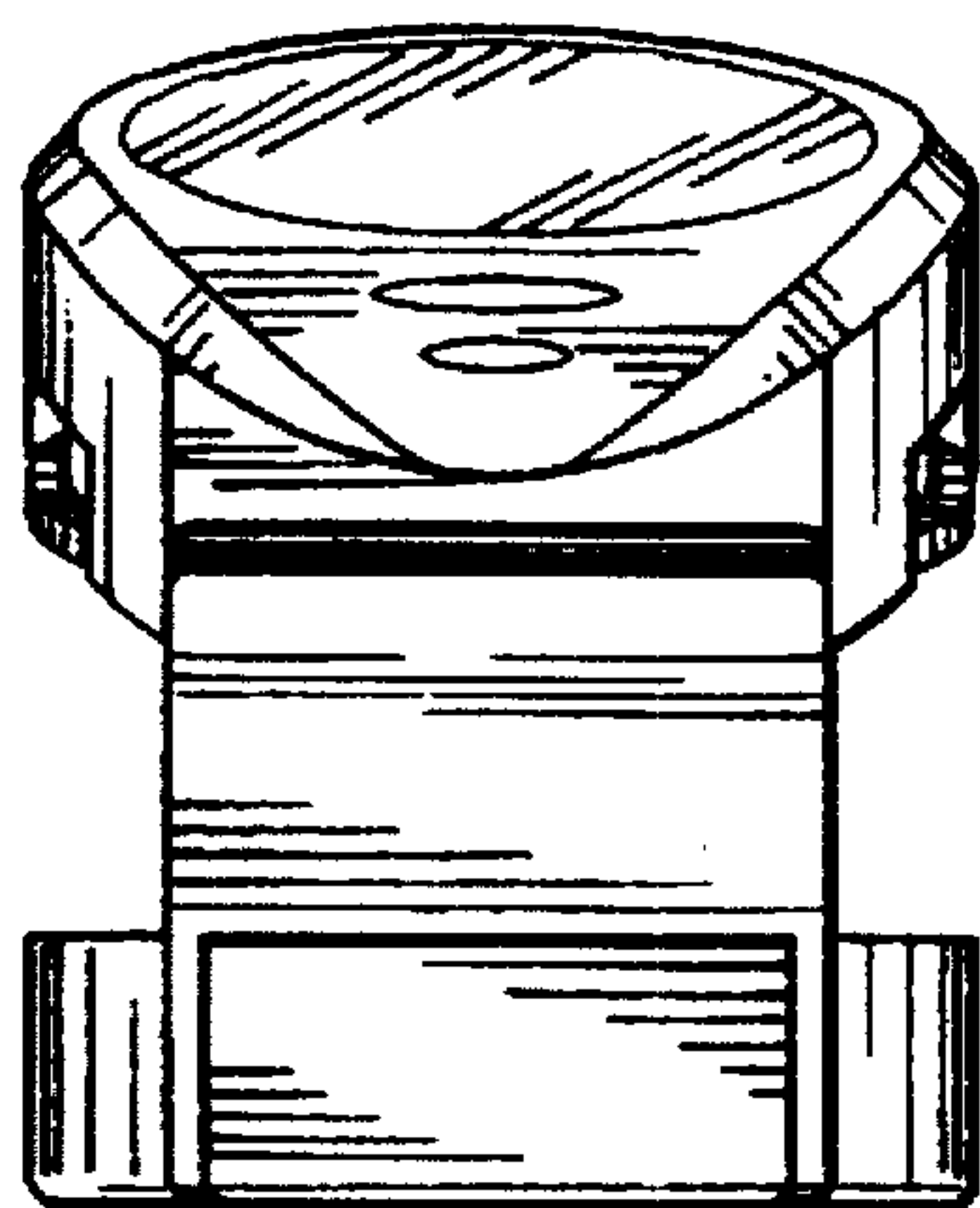


FIG. 7